

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _{RM}		
Average Rectified Output Current (See Figure 1)	I _O	0.2	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	5.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance	R _{θJS}	18	°C/W
Thermal Resistance Junction to Soldering (Note 5)	R _{θJA}	263	
Thermal Resistance Junction to Ambient (Note 6)			
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V _F	-	0.34 - 0.39	0.40 0.48 0.45	V	I _F = 0.1A, T _J = +25°C I _F = 0.2A, T _J = +25°C I _F = 0.2A, T _J = 125°C
Leakage Current (Note 7)	I _R	-	4 0.5	50 10	μA mA	V _R = 30V, T _J = +25°C V _R = 30V, T _J = +125°C

Notes: 5. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
6. FR-4 PCB, 2oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
7. Short duration pulse test used to minimize self-heating effect.

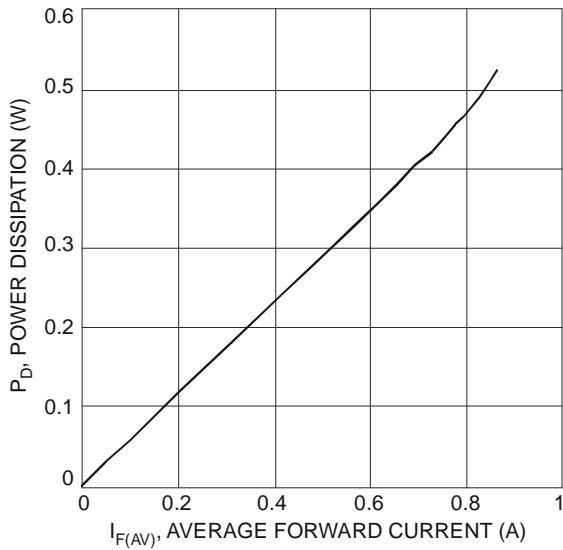


Fig. 1 Forward Power Dissipation

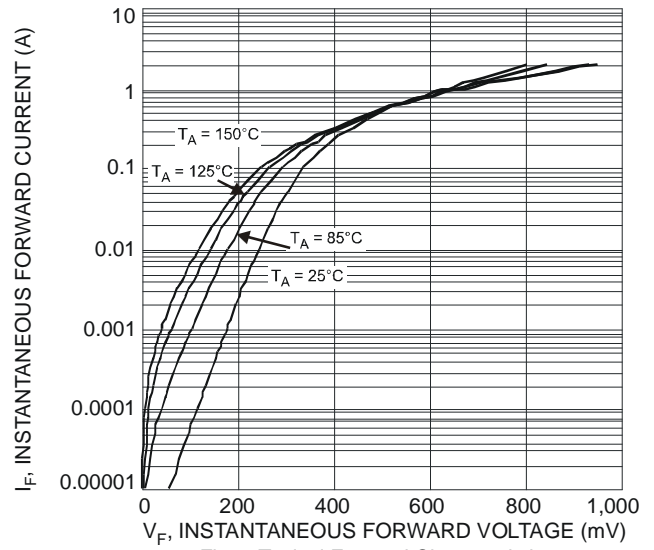


Fig. 2 Typical Forward Characteristics

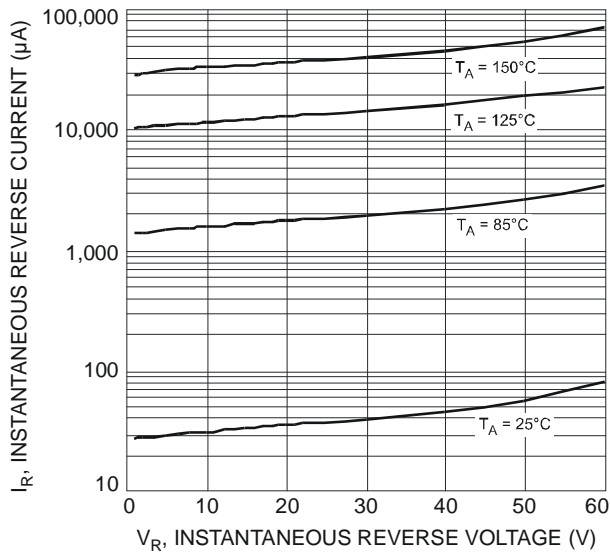


Fig. 3 Typical Reverse Characteristics

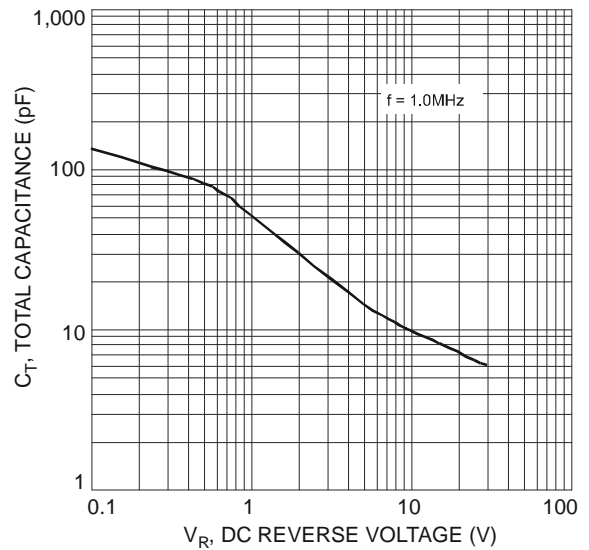


Fig. 4 Total Capacitance vs. Reverse Voltage

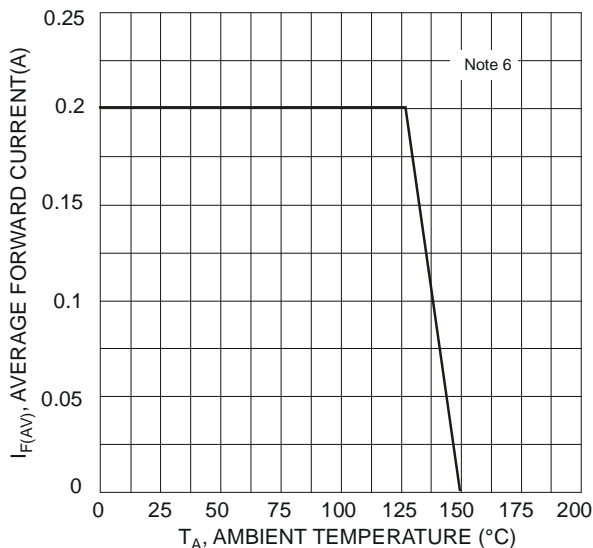


Fig. 5 Forward Current Derating Curve

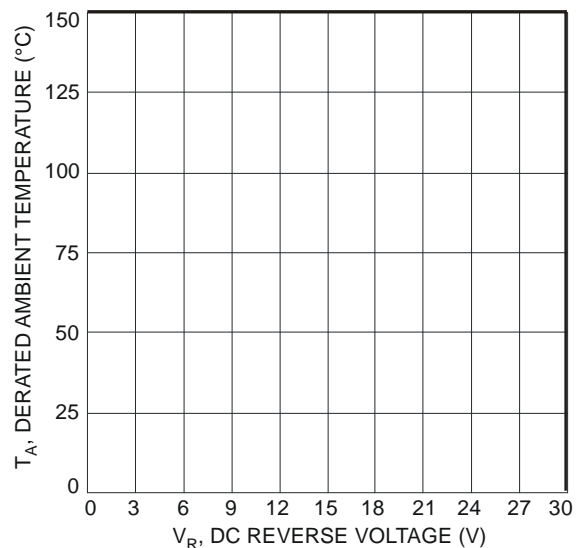
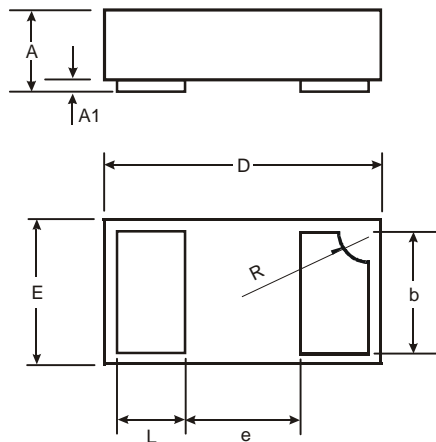


Fig. 6 Operating Temperature Derating

Package Outline Dimensions

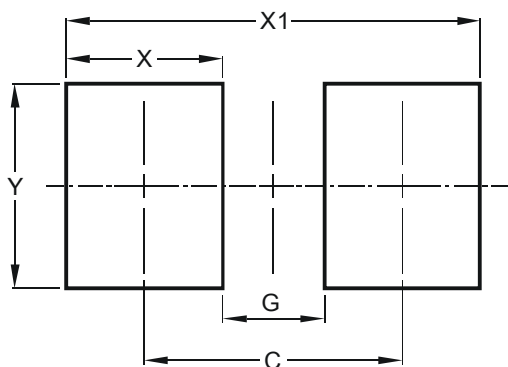
Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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